

Features

- Very low conduction losses
- Low forward voltage drop
- Low thermal resistance
- High specified avalanche capability
- High integration
- ECOPACK[®]2 compliant component

Description

The STPS30H100DJF is a power Schottky rectifier suited for switch mode power supply and high frequency DC to DC converters.

Housed in a PowerFLAT[™] package, this device is intended to be used in adaptors requiring good efficiency at both low and high load. Its low profile was especially designed to be used in applications with space-saving constraints.

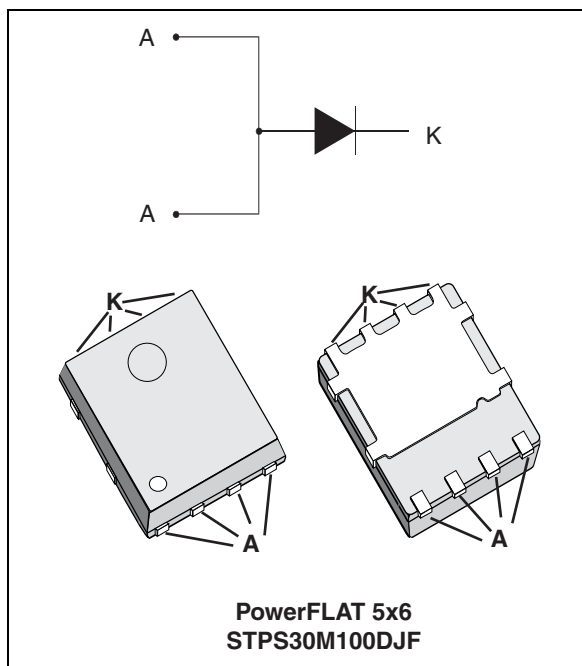


Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	30 A
V_{RRM}	100 V
T_j	150 °C
$V_F(\text{typ})$	0.56 V

TM: PowerFLAT is a trademark of STMicroelectronics

1 Characteristics

Table 2. Absolute ratings (limiting values, anode terminals short circuited)

Symbol	Parameter	Value	Unit	
V _{RRM}	Repetitive peak reverse voltage	100	V	
I _{F(RMS)}	Forward rms current	45	A	
I _{F(AV)}	Average forward current $\delta = 0.5$	T _c = 100 °C	30	A
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal	250	A
P _{ARM}	Repetitive peak avalanche power	t _p = 1 μ s, T _j = 25 °C	3700	W
V _{ARM}	Maximum repetitive peak avalanche voltage	t _p < 1 μ s, T _j < 150 °C I _{AR} < 9.3A	120	V
T _{stg}	Storage temperature range	-65 to +175	°C	
T _j	Maximum operating junction temperature ⁽¹⁾	150	°C	

1. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Junction to case	2	°C/W

Table 4. Static electrical characteristics (anode terminals short circuited)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit	
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}	-	-	6	μ A
		T _j = 125 °C		-	2.5	6.5	mA
V _F ⁽¹⁾	Forward voltage drop	T _j = 25 °C	I _F = 15 A	-	-	0.76	V
		T _j = 125 °C		-	0.56	0.62	
		T _j = 25 °C	I _F = 30 A	-	-	0.84	
		T _j = 125 °C		-	0.63	0.71	

1. Pulse test: t_p = 380 μ s, δ < 2%

To evaluate the conduction losses use the following equation:

$$P = 0.60 \times I_{F(AV)} + 0.00367 \times I_{F(RMS)}^2$$

Figure 1. Average forward power dissipation versus average forward current

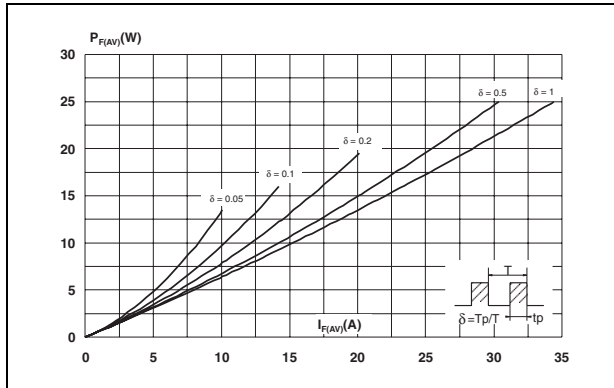


Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$)

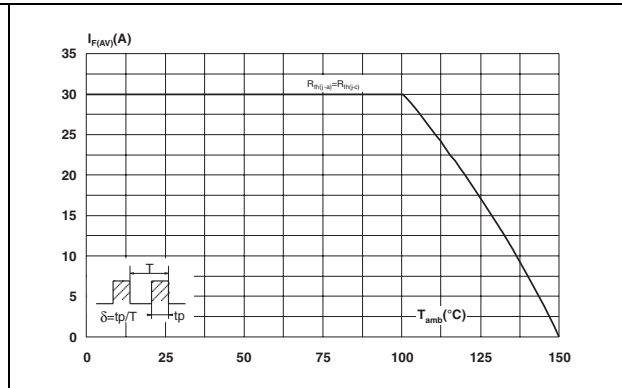


Figure 3. Relative variation of thermal impedance junction to case versus pulse duration

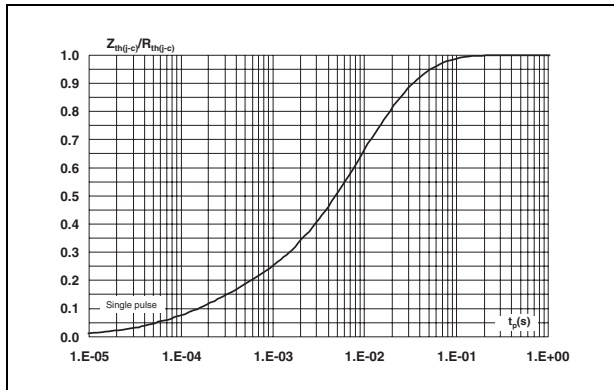


Figure 4. Reverse leakage current versus reverse voltage applied (typical values)

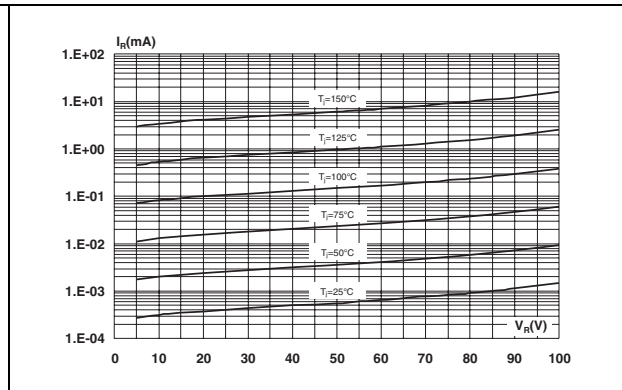


Figure 5. Junction capacitance versus reverse voltage applied (typical values)

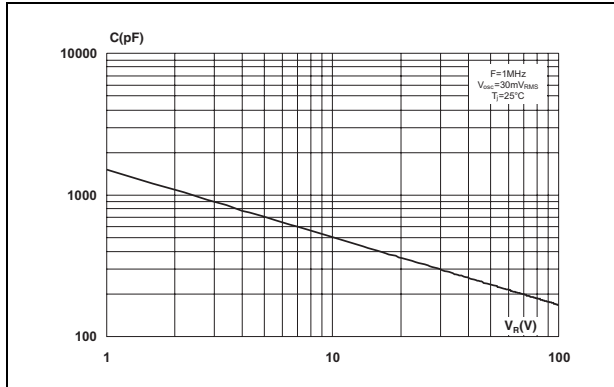


Figure 6. Forward voltage drop versus forward current

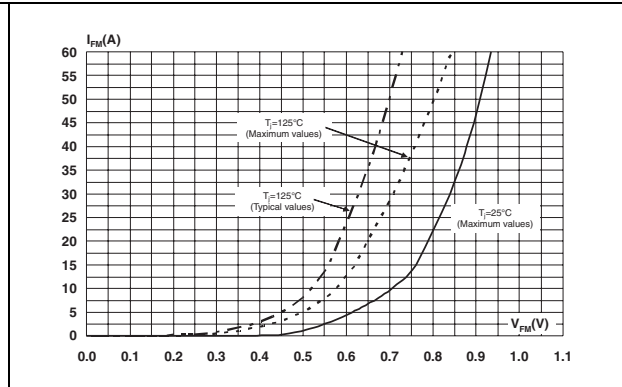
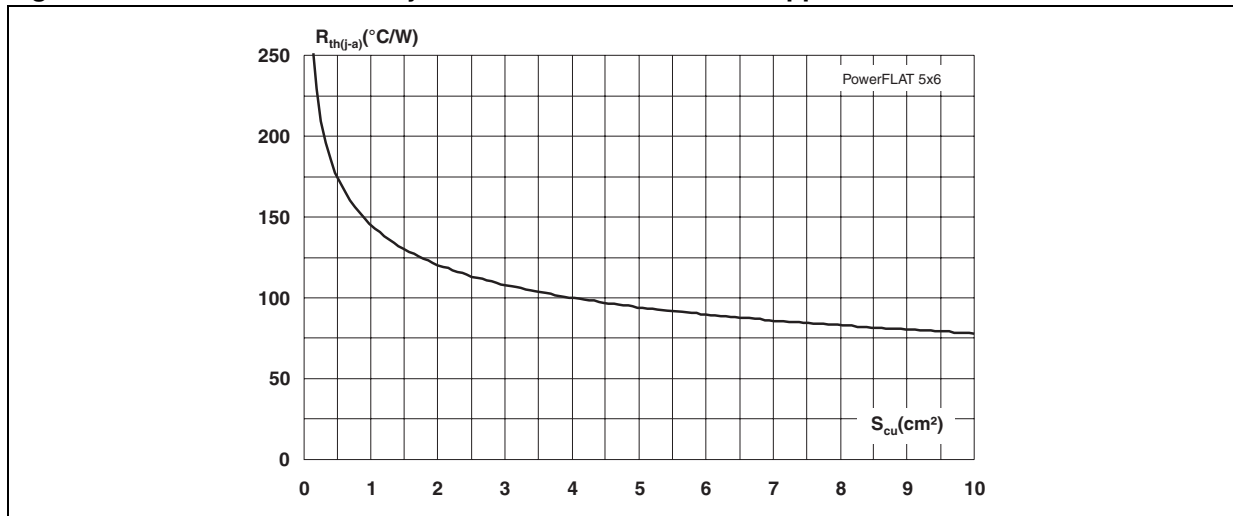


Figure 7. Thermal resistance junction to ambient versus copper surface under tab



2 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 5. PowerFLAT 5x6 dimensions

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.80		1.00	0.031		0.039
A1	0.02		0.05	0.001		0.002
A2		0.25		0.010		
b	0.30		0.50	0.012		0.020
D		5.20		0.205		
D2	4.11		4.31	0.162		0.170
e		1.27		0.050		
E		6.15		0.242		
E2	3.50		3.70	0.138		0.146
L	0.50		0.80	0.020		0.031
K	1.275		1.575	0.050		0.062

Figure 8. Footprint (dimensions in mm)

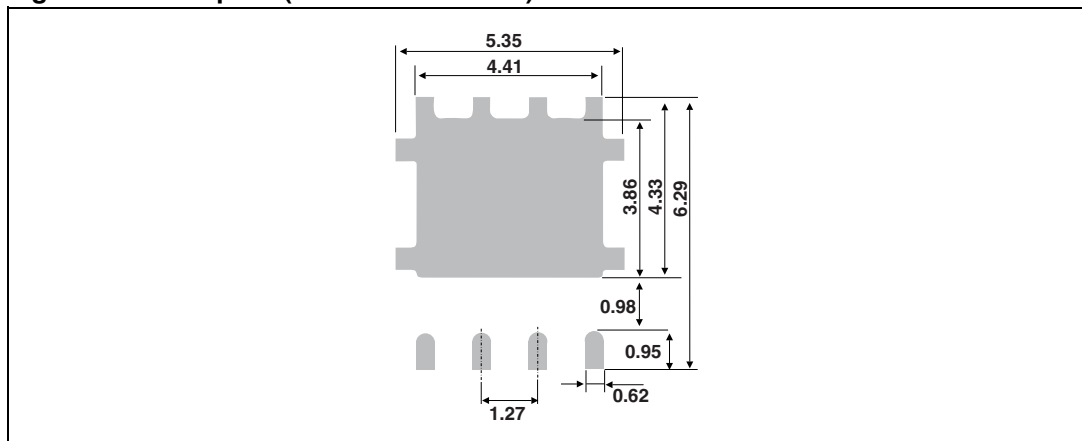
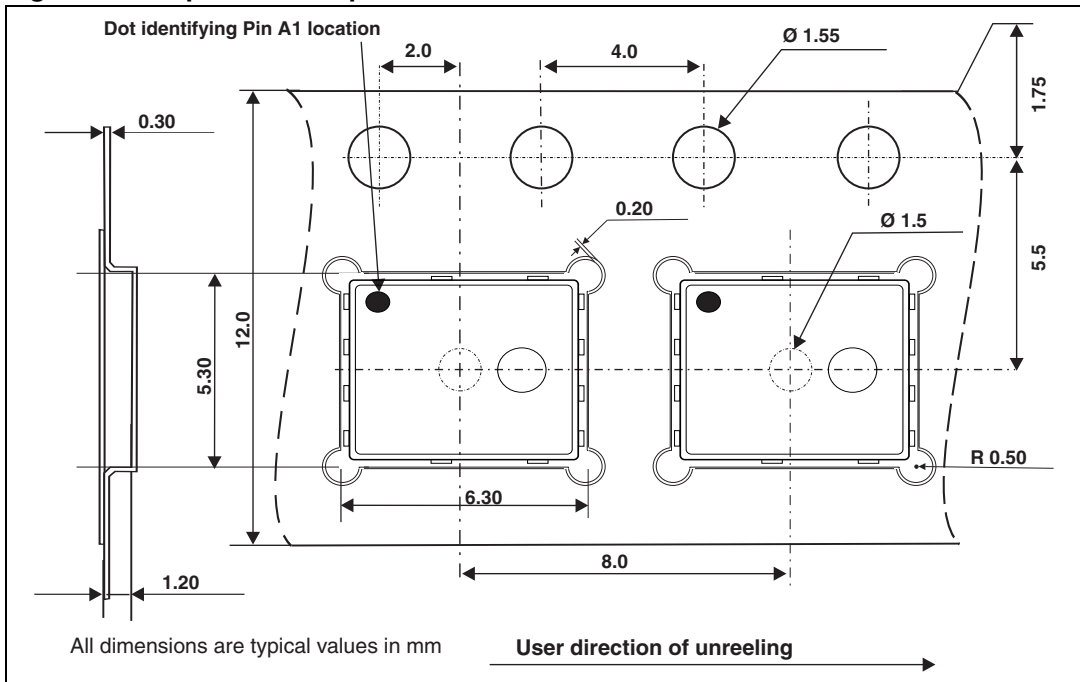


Figure 9. Tape and reel specifications



3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS30H100DJF-TR	PS30 H100	PowerFLAT 5x6	95 mg	3000	Tape and reel

4 Revision history

Table 7. Document revision history

Date	Revision	Changes
29-Mar-2012	1	Initial release.

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